Tyrone Camarero Specifications

Camarero DS3007R-48R4

Key features

- Dual socket R3 (LGA 2011) supports Intel® Xeon® processor E5-2600 v4/v3 family
- Intel® C612 chipset
- Up to 3TB ECC 3DS LRDIMM, up to DDR4- 2400MHz; 24x DIMM slots
- 2x PCI-E 3.0 x16, 3x PCI-E 3.0 x8, and 1x PCI-E 2.0 x4 (in x8) slot
- Ouad LAN w/Intel® i350 GbE
- I/O ports: 2x SuperDOM, 1x VGA, 2x COM, 2x USB 3.0, 4x USB 2.0
- 8x 3.5" Hot-swap SATA3 HDD Bays; 8x 2.5" Hot-swap SAS3 drives in mobile rack; 1x 5.25" drive bay
- 920W Redundant Power Supplies Platinum Level (94%)
- **Tower or Rackmount**







Processor/Cache

Dual socket R3 (LGA 2011) supports Processor

Intel® Xeon® processor E5-2600 v4/ v3 family

Chipset

Intel® C612 chipset Chipset

System Memory

Memory Capacity 24x 288-pin DDR4 DIMM slots

Up to 3TB ECC 3DS LRDIMM,

768 ECC RDIMM

Expansion Slots

PCI-Express 2x PCI-E 3.0 x16 (Full-height, Full-length)

3x PCI-E 3.0 x8 (Full-height, Full-length)

1x PCI-E 2.0 x4 (in x8)

Integrated On-Board

SATA SATA3 (6Gbps); RAID 0, 1, 5, 10 SAS LSI 3108 SAS3 (12Gbps) controller; HW RAID 0, 1, 5, 6, 10, 50, 60 LAN 4x RJ45 Gigabit Ethernet LAN ports, 1x RJ45 Dedicated IPMI LAN port

Add-on Options

Optical Drive None

Front Panel

LED Indicators Power LED, Hard drive activity LED,

> 2x Network activity LEDs, System information(overheat/UID)LED,

Power Fail LED

Power On/Off button, System Reset button **Buttons**

Drive Bays

HDD Bays 8x 3.5" Hot-swap SATA3 drive trays,

8x 2.5" Hot-swap SAS3 drives in mobile

rack,1x 5.25" drive bay (optional devices)

Power Supply

920W Redundant Power Supplies Platinum Level (94%)

Cooling System

3x 8cm Hot-swap redundant PWM Cooling Fans, 2x 8cm Hot-swap Rear Exhaust PWM Fans & air shroud

Form Factor

Form Factor 4U Rackmountable / Tower,

Optional Rackmount Kit

Width: 7.0" (178mm), Height: 17.2" (437mm), Depth: 25.5" (648mm)

Email: info@tyronesystems.com For more/current product information, visit www.tyronesystems.com

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